

## ABSTRACT

A semiconductor device is provided which comprises a heat-radiative support plate 5; and first and second semiconductor elements 1 and 2 mounted and layered on support plate 5 for alternate switching of first and second semiconductor elements 1 and 2. The arrangement of piling and securing first and second semiconductor elements 1 and 2 on support plate 5 improves integration degree of semiconductor elements 1 and 2, and reduces the occupation area on support plate 5. Alternate switching of first and second semiconductor elements 1 and 2 controls heat produced from first and second semiconductor elements 1 and 2 because one of first and second semiconductor elements 1 and 2 is turned on, while the other is turned off.